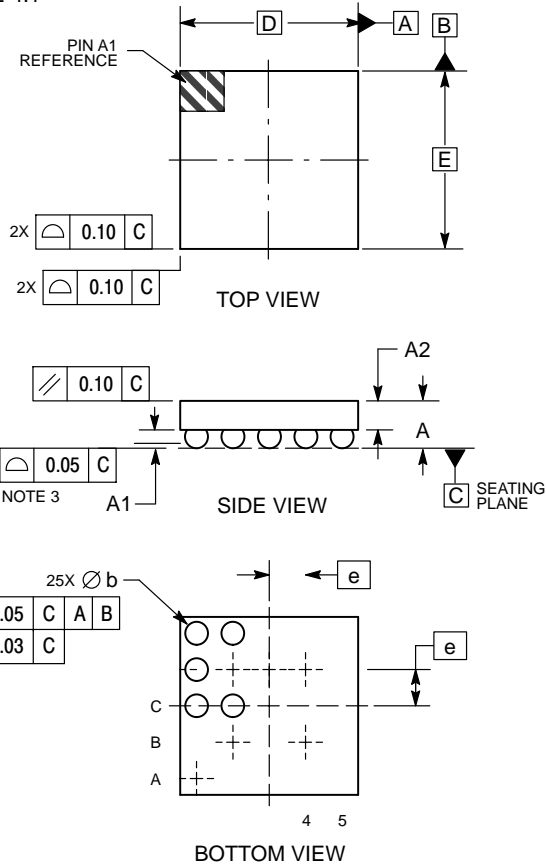


WLCSP25, 2.06x2.06
CASE 567FZ
ISSUE O

DATE 17 JUL 2012

SCALE 4:1

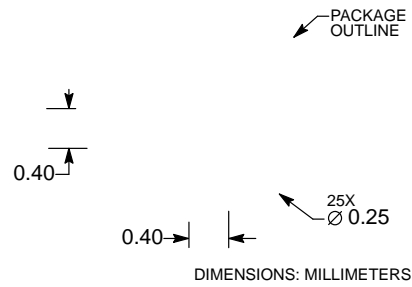


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	i i i	0.60
A1	0.17	0.23
A2	0.36 REF	

b	0.24	0.29
D	2.06 BSC	
E	2.06 BSC	
e	0.40 BSC	

RECOMMENDED
SOLDERING FOOTPRINT*



*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.